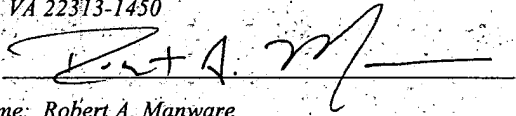


APPARATUS AND METHOD FOR MANAGING VOLTAGE BUSES

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APPARATUS AND METHOD FOR MANAGING VOLTAGE BUSES

BACKGROUND OF THE INVENTION

5 1. Field Of The Invention

The present invention relates generally to semiconductor devices and, more particularly, to the distribution of power in array and periphery sections of a semiconductor device, such as a memory device.

10 2. Description of The Related Art

This section is intended to introduce the reader to various aspects of art which may be related to various aspects of the present invention which are described and/or claimed below. This discussion is believed to be helpful in providing the reader with background information to facilitate a better understanding of the various aspects of the present invention. Accordingly, it should be understood that these statements are to be read in this light, and not as admissions of prior art.

Microprocessor-controlled integrated circuits are used in a wide variety of applications. Such applications include personal computers, telephones, vehicle control systems, networks, and a host of other consumer products. Typically, microprocessors are essentially generic devices that perform specific functions under the control of a software program. This program is stored in a memory device that is coupled to the microprocessor. Not only does the microprocessor access one or more memory devices to retrieve the

program instructions, but it also stores and retrieves data created during execution of the program in the memory devices.

It should be understood that memory devices, which may be a semiconductor
5 chip, include integrated circuits that are typically mass produced through fabrication
processes. In forming the chip, different materials are layered together to form various
structures or circuitry within the chip. These structures are connected together to
exchange signals, distribute power within the chip and receive power from external
devices, among other things. Additionally, the semiconductor chip may be divided into
10 different sections, such as the array section and the periphery section. The array section
may include memory structures, such as memory cells and banks that are used to store data,
while the periphery section may include larger structures that support the array section, such
as drivers, interconnects between circuitry, decoders or other similar circuitry.

15 Regardless of the specific structures within the semiconductor chip being fabricated,
it is often desirable to conserve power and to ensure that the power distributed to various
circuits is provided in a consistent and steady manner. For instance, in a personal
computing device, the configuration and layout of components may affect the operation
and efficiency of the device. During a power-up phase, different sections of the chip,
20 such as the periphery and array sections, may not reach a specified voltage at the same
time. This variation in time may result in the chip taking longer to power up from an
initialization or standby mode to an operation mode because one of the sections takes

longer to reach the operational voltage. As a result, these inefficiencies may reduce the amount of time that the device is able to operate in an active or standby mode.

BRIEF DESCRIPTION OF THE DRAWINGS

5 The foregoing and other advantages of the present technique may become apparent upon reading the following detailed description and upon reference to the drawings in which:

FIG.1 illustrates a block diagram of an exemplary processor-based device in
10 accordance with the present technique;

FIG. 2 illustrates a block diagram of an exemplary embodiment of a semiconductor chip used in the processor-based device of FIG. 1;

15 FIG. 3 illustrates a block diagram of an alternative exemplary embodiment of a semiconductor chip used in the processor-based device of FIG. 1 in accordance with aspects of the present technique;

FIG. 4 illustrates a block diagram depicting a more detailed exemplary
20 embodiment of the power distribution system in the semiconductor chip of FIG. 3 in accordance with aspects of the present technique;

FIG. 5 illustrates a graph of time periods associated with various circuits to reach a specified voltage;

FIG. 6 illustrates a schematic diagram depicting an exemplary embodiment of the bridge circuit of FIGs. 3 and 4 in accordance with aspects of the present technique; and

FIG. 7 illustrates a process flow diagram of the bridge circuit of FIGs. 3 and 4 in accordance with aspects of the present technique.

DETAILED DESCRIPTION OF SPECIFIC EMBODIMENTS

One or more specific embodiments of the present invention will be described below. In an effort to provide a concise description of these embodiments, not all features of an actual implementation may be described in the specification. It should be appreciated that in the development of any such actual implementation, as in any engineering or design project, numerous implementation-specific decisions are made to achieve the developers' specific goals, such as compliance with system-related and business-related constraints, which may vary from one implementation to another. Moreover, it should be appreciated that such a development effort might be complex and time consuming, but would nevertheless be a routine undertaking of design, fabrication, and manufacture for those of ordinary skill having the benefit of this disclosure.

The present technique is an improved approach for managing voltage buses to conserve power and to ensure that the power distributed to various circuits is provided in a

consistent and steady manner. Under the present technique, a bridge circuit may be utilized to connect voltage buses together or isolate voltage buses from each other to enhance the operation of circuitry within a semiconductor chip. The bridge circuit may be controlled by control signals associated with different modes of operation within the semiconductor chip.

5 As a result of the bridge circuit, the operation of the semiconductor chip may be enhanced because the problems associated with different voltages being applied to the different circuitry may be diminished. In addition, duplicate components may be removed to further reduce leakage within the semiconductor chip.

10 Turning now to the drawings, and referring initially to FIG. 1, a block diagram depicting an exemplary processor-based device, generally designated by the reference numeral 100, is illustrated. The device 100 may be any of a variety of different types of devices, such as a computer, a pager, a cellular telephone, a personal organizer, a control circuit, etc. In a typical processor-based device, a processor 102, such as a
15 microprocessor, controls many of the functions of the device 100.

The device 100 typically includes a power supply 104 that delivers power to the device. The type of power supply 104 may vary depending on the function of the device 100. For instance, if the device 100 is portable, the power supply 104 may
20 advantageously include permanent batteries, replaceable batteries, and/or rechargeable batteries. The power supply 104 may also include an A/C adapter, so that the device 100 may be plugged into a wall outlet, for instance. In addition, the power supply 104 may

also include a D/C adapter, so that the device 100 may be plugged into a vehicle's cigarette lighter, as well. Alternatively, if the power supply 104 is not portable, it may be configured with the A/C adapter to be plugged into a wall outlet.

5 Various other devices may be coupled to the processor 102, depending upon the functions that the device 100 performs. For instance, a user interface 106 may be coupled to the processor 102 to receive information. The user interface 106 may include buttons, switches, a keyboard, a light pen, a mouse, and/or a voice recognition system, for instance. A display 108 may also be coupled to the processor 102 to present information
10 to the user. The display 108 may include an LCD display, a CRT, LEDs, and/or an audio display. Furthermore, an RF subsystem/baseband processor 110 may also be coupled to the processor 102 to communicate with other devices through a wireless link. The RF subsystem/baseband processor 110 may include an antenna that is coupled to an RF receiver and to an RF transmitter (not shown). A communications port 112 may also be
15 coupled to the processor 102 to communicate with other devices through a physical link. The communications port 112 may be adapted to couple with one or more input/output (I/O) devices 114, such as a modem, a printer, or a computer, for instance.

Because the processor 102 controls the functioning of the device 100 generally
20 under the control of software programming, memory is coupled to the processor 102 to store and to facilitate execution of software programs. For instance, the processor 102 may be coupled to volatile memory 116, which may include dynamic random access

memory (DRAM) and/or static random access memory (SRAM). The amount of DRAM and SRAM may depend on the specific design of the device 100. The processor 102 may also be coupled to non-volatile memory 118. The non-volatile memory 118 may include a read only memory (ROM), such as an erasable programmable ROM, to be used in
5 conjunction with the volatile memory 116. The size of the ROM is typically selected to be just large enough to store any necessary operating system, application programs, and fixed data. The volatile memory 116, on the other hand, is typically quite large so that it can store dynamically loaded applications. Additionally, the non-volatile memory 118 may include a high capacity memory, such as a disk or a tape drive memory.

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In operating the processor-based device 100, it may be advantageous to conserve power so that the device 100 may remain active longer. As such, the components of the device 100 may be designed to reduce redundant components, to operate more efficiently, and to consume less power. For instance, the volatile memory 116 may be designed to
15 remove duplicative circuits or to share circuits when the device 100 is operating in different modes, such as a power-up mode, an idle mode, an activation mode, a read/write burst mode, a standby mode, or a power-down mode. By reducing the duplicative circuits, the power lost or consumed by the redundant circuits may be eliminated, as described further below. As a result, the device 100 may remain active for longer periods
20 of time and may operate more efficiently on a limited power source.

In addition, each of the components associated with the device 100 may have different activation time periods before which the component may become operational. For instance, the volatile memory 116 may become active after the communication port 112 because different sections of the volatile memory 116 have different activation time periods that prolong its activation. To reduce the delay in activating the device 100, the volatile memory 116 may be designed to maintain a voltage on various components or to operate in different modes, which reduce the amount of time consumed to activate or initialize the device 100.

As mentioned previously, a processor-based device 100 may include integrated circuits or structures in the semiconductor chips, which are utilized to provide different functionalities to the device 100. For instance, the semiconductor chips in the volatile memory 116 may utilize the power from the power supply 104 to perform specific functions, such as storing data or software programs. As such, improvements in the power distribution in the semiconductor chips may reduce the power consumed by the volatile memory 116 and provide faster access to the information stored in the volatile memory 116. The power distribution in a semiconductor chip is explained in greater detail with FIG. 2.

Turning now to FIG. 2, a block diagram of an exemplary embodiment of a power distribution system in a semiconductor chip is illustrated. In this power distribution system 200, a semiconductor chip 202, which may be a portion of the processor-based

device 100 of FIG. 1, may receive power from the power supply 104, which is discussed above in FIG. 1. The power delivered to the semiconductor chip 202 may be distributed to two different sections of the chip 202, which may include an array section and a periphery section. The array section may include memory banks for DRAM, SRAM, or other memory types. The periphery section may include circuitry and other structures used to support the array section, such as drivers, interconnects between circuitry, decoders or other similar circuitry.

The array and periphery sections of the semiconductor chip 202 may also include components to distribute power within the semiconductor chip 202. For instance, power may be delivered from the power supply 104 to an array power amplifier 204 and a periphery power amplifier 206. Each of the power amplifiers 204 and 206 may represent multiple power amplifiers or power regulators that are assigned to different sections of the chip 202. The power amplifiers 204 and 206 may modify the voltage and drive it to a respective array voltage bus 208 or a periphery voltage bus 210. The array voltage bus 208 may apply a specified voltage to an array circuitry 212, while the periphery voltage bus 210 may apply a specified voltage to a peripheral circuitry 214. Also, the array voltage bus 208 may connect to an array standby power amplifier 216 that supplies the array voltage bus 208 with voltage when the semiconductor chip 202 is in a standby mode. The periphery voltage bus 210 may include a periphery standby power amplifier 218 that supplies the periphery circuitry 214 with voltage when the semiconductor chip 202 is in a standby mode.

During the normal mode of operation, which may include an activation mode or a read/write burst mode, the voltage buses 208 and 210 may supply different voltages to the circuitry 212 and 214. The activation mode may include executing commands in the array circuitry 212 and the periphery circuitry 214, while the read/write mode may include accessing data from or providing data to the array circuitry 212 and the periphery circuitry 214. In these modes, a first voltage may be applied to the array circuitry 212 from the array voltage bus 208, while a second voltage may be applied to the periphery circuitry 214 from the periphery voltage bus 210. The voltages applied to the array circuitry 212 and periphery circuitry 214 may be different because each of the circuits has a different capacitance. The capacitances differ because each circuitry 212 and 214 has different components coupled to the respective circuitry 212 and 214. As a result, the voltage levels on the array circuitry 212 and the periphery circuitry 214 may differ, which may produce errors within the semiconductor chip 202.

Also, during a standby or an inactive mode of operation, which may include a power-up mode, an idle mode, a standby mode, and/or a power-down mode, the voltage buses 208 and 210 may provide different voltages to the circuitry 212 and 214. The standby mode may maintain power to specific components, while other components are shut down. The power-up mode may distribute power to the various components within the array circuitry 212 and the periphery circuitry 214, while the power-down mode may reduce or stop the voltage from being applied to components within the array circuitry

212 and the periphery circuitry 214. The idle mode may maintain power to the various components, while waiting for other instructions to be received. With each of these modes, a first voltage may be provided to the array circuitry 212 from the array standby amplifier 216, while a second voltage may be provided to the periphery circuitry 214 from the periphery standby amplifier 218. During these modes, the voltages applied to the array circuitry 212 and periphery circuitry 214 may also be different because the array standby amplifier 216 and the periphery standby amplifier 218 are each isolated from one another and depend on the respective capacitances of the circuitry 212 and 214. As a result of these voltage differences, operational problems may again be present in the array circuitry 212 and the periphery circuitry 214.

In addition, in each of these modes, the array circuitry 212 and the periphery circuitry 214 may each have redundant power amplifiers 204 and 206 and standby amplifiers 216 and 218 that provide duplicative services for the respective circuitry 212 and 214. As a result, each of the power amplifiers 204 and 206 and standby power amplifiers 216 and 218 may consume additional amounts of power. As such, the redundant components may further increase the power consumed by the semiconductor chip 202.

To enhance the operation of the semiconductor chip 202, a bridge circuit may be implemented that enables the voltage buses 208 and 210 to share components and to maintain the same voltage level on each of the voltage buses 208 and 210. The bridge

circuit may act as a short during certain modes to allow components, such as power amplifiers 204 and 206 and standby power amplifiers 216 and 218 to share components while maintaining redundancy. Also, by acting as a short, the bridge circuit may equalize the voltage between the array circuitry 212 and periphery circuitry 214 to minimize the errors that result from different voltages being applied to the circuitry 212 and 214.

Alternatively, the bridge circuit may isolate the buses 208 and 210 from each other during other modes. An alternative exemplary embodiment relating to the distribution of power in a semiconductor chip with components, such as a bridge circuit, is explained in greater detail with respect to FIG. 3.

In FIG. 3, a block diagram depicting an alternative exemplary embodiment of the power distribution in a semiconductor chip is illustrated. In this diagram 300, a semiconductor chip 302, which may be a portion of the processor-based device 100 of FIG. 1, may include a bridge circuit 304 to improve the operation of the semiconductor chip 302. Similar to the semiconductor chip 202 in FIG. 2, the semiconductor chip 302 may include various amplifiers 204, 206, and 218, buses 208 and 210, and circuitry 212 and 214, which may function as discussed above with regard to FIG. 2. Also, the semiconductor chip 302 may receive power from the power supply 104 in a manner similar to the semiconductor chip 202 (FIG. 2).

However, to provide enhanced functionality, the bridge circuit 304 may be coupled between the array power amplifier 204 and the array voltage bus 208 at a node

306 and coupled between the periphery power amplifier 206 and the periphery voltage bus 210 at a node 308. By coupling the bridge circuit 304 between the power amplifiers 204 and 206 and respective voltage buses 208 and 210, the voltages applied to the array circuitry 212 and the periphery circuitry 214 may be maintained at approximately the same level in certain modes of operation. In other modes of operation, however, the bridge circuit 304 may remain open to provide isolation. The isolation may prevent noise from one of the buses 208 and 210 from affecting the sensitive circuitry on the other bus 208 and 210. For instance, by isolating the buses 208 and 210, the bridge circuit 304 may prevent noise on the array voltage bus 208 from interfering with the operation of periphery circuitry 214 that is sensitive to voltage fluctuations. Thus, the bridge circuit 304 may enhance the operation of the semiconductor chip 302.

For instance, during the normal mode of operation, which may include the activation mode or the read/write burst mode, the power amplifiers 204 and/or 206 may apply voltages to the array circuitry 212 and the periphery circuitry 214, respectively. If the bridge circuit 304 is closed, the bridge circuit 304 may short the two voltage buses 208 and 210 together. In this instance, the voltage applied to the array circuitry 212 and periphery circuitry 214 is approximately equal because the voltage buses 208 and 210 are coupled together by the bridge circuit 304. As such, the errors resulting from voltage variations in the circuitry 212 and 214 may be reduced. In addition, the array circuitry 212 and periphery circuitry 214 may share the standby amplifier 218 and/or power amplifiers 204 and 206, which may reduce the amount of power consumed by redundant

components within the semiconductor chip 302. The sharing of standby amplifier 218 or power amplifiers 204 and 206 may allow the voltage buses 208 and 210 to share components and still provide some redundancy. Conversely, if the bridge circuit 304 is open, then the voltage buses 208 and 210 may be isolated from one another to provide
5 protection between the buses 208 and 210 for noise isolation, for example.

During the standby mode of operation, which may include a power-up mode, an idle mode, a standby mode, and/or a power-down mode, the bridge circuit 304 may be closed to act as a short, and the standby amplifier 218 may supply power to the array
10 circuitry 212 and the periphery circuitry 214. As with the normal mode of operation, the voltage applied to the array circuitry 212 and periphery circuitry 214 may be substantially equal because the standby amplifier 218 is supplying power to the array 212 and periphery circuitry 214. As such, the operation of the circuitry 212 and 214 may be enhanced because operational problems associated with differences in voltage levels on
15 the different circuitry 212 and 214 may be reduced.

In addition, it should be noted that the standby power amplifier 218 may be removed and the standby power amplifier 216 may be attached to the array circuitry 216 in an alternative embodiment. In this embodiment, the standby power amplifier 216 may
20 supply power from the array circuitry 212 to the periphery circuitry 214 to provide the advantage discussed above. For a better understanding of the operation of the bridging circuit 304, a more detailed embodiment of the power distribution system in a

semiconductor chip 302 is explained with regard to the different modes of operation in FIG. 4.

A block diagram depicting a more detailed embodiment of the bridging circuit along with the various other components in a semiconductor chip, such as the semiconductor chip 302 of FIG. 3, is illustrated in FIG. 4. In this diagram, a power distribution system 402 of a semiconductor chip is shown. Power may be received by the power distribution system 402, in a manner similar to the discussion in FIG. 3. For instance, power may be distributed by the power distribution system 402 through the periphery power amplifier 206 to the periphery circuitry 214 and an array power amplifier 204 to the array circuitry 212. Also, as mentioned above, the power may be distributed to the array circuitry 212 and the periphery circuitry 214 through the standby power amplifier 218 during certain modes of operation.

In this embodiment, additional devices may be utilized to provide signals for operating the bridge circuit 304. For instance, one device that may be utilized may be a voltage detector 404, which may be coupled to the periphery voltage bus 210. The voltage detector 404 may be used to determine the voltage level on the periphery voltage bus 210, which may be used as an input control signal to the control logic that determines the mode of operation. Additionally, a periphery capacitor 406 may represent the capacitance of the periphery voltage bus 210, while an array capacitor 408 may represent

the capacitance of the array voltage bus 208. The capacitors 406 and 408 may vary depending on the specific components in the respective circuits.

Also, the array voltage bus 208 and the periphery voltage bus 210 may connect
5 the bridge circuit 304 and other circuitry that is utilized to operate the bridge circuit 304 together during different modes of operation. For instance, the bridge circuit 304, which may be one possible embodiment of a bridge circuit, may operate to isolate buses 208 and 210 or may operate to short buses 208 and 210 together, depending on the specific control signals received by the bridge circuit 304. To control the state of the bridge circuit 304,
10 the voltage detector 404 along with a voltage detector 410 and a regulator control 412 may be coupled to the bridge circuit 304. The voltage detector 410 may be utilized to monitor voltage levels on the array voltage bus 208, the periphery voltage bus 210, and/or other buses. The voltage detector 404 or 410 may send a power-up control signal to the bridge circuit 304, which may be utilized to indicate the power-up mode or the
15 initialization mode. The regulator control 412, which may be coupled to control circuitry and/or the processor, may send a control signal to the bridge circuit 304 to place the bridge circuit 304 into various states or modes, such as power-up mode, idle mode, activation mode, read/write burst mode, standby mode, and power-down mode, for example. In each of these modes, the bridge circuit 304 may couple the buses 208 and
20 210 together or may isolate the buses 208 and 210 from each other, depending on the control signal or condition sent to the bridge circuit 304.

For example, during the activation and/or the read/write burst modes, power may be delivered to the array voltage bus 208 and the periphery voltage bus 210 from the respective power amplifiers 204 and 206. Also, the regulator control 412 or the voltage detector 404 or 410 may send a control signal to the bridge circuit 304 that indicates an open circuit condition. As noted above, the activation mode may include executing commands in the circuitry 212 and 214, while the read/write mode may include accessing data from or delivering data to the circuitry 212 or 214. In each of these modes, the voltage on the array voltage bus 208 and the periphery voltage bus 210 may be different because the bridge circuit 304 is open and the buses 208 and 210 are isolated from the other.

Alternatively, during the standby mode, power may be delivered to the array voltage bus 208 and the periphery voltage bus 210 through the standby power amplifier 218. The regulator control 412 or the voltage detector 404 or 410 may send a control signal to the bridge circuit 304 to couple the array voltage bus 208 and the periphery voltage bus 210 together. This may allow the standby mode to maintain power to specific components, while other components are shut down. As such, the voltage applied to the array voltage bus 208 and the periphery voltage bus 210 may be about the same because the bridge circuit 304 couples the buses 208 and 210 together.

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Also, during the power-up mode, the idle mode, and the power-down mode, power may be delivered to buses 208 and 210 through the respective power amplifiers

204 and 206. The regulator control 412 or the voltage detector 404 or 410 may each send a control signal to the bridge circuit 304 to couple the array voltage bus 208 and the periphery voltage bus 210 together. The power-up mode and power-down mode may distribute/reduce the power being supplied to various components within the array
5 circuitry 212 and the periphery circuitry 214, as discussed above. Likewise, the idle mode may maintain power to the various components, while the power distribution system 402 is waiting for other instructions to be received. In each of these modes, the voltage supplied to the buses 208 and 210 may be approximately equal because the bridge circuit 304 couples the buses 208 and 210 together.

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Advantageously, by implementing the bridging circuit 304 in these various modes, the power distribution system 402 may enhance the operation of the semiconductor chip. The bridging circuit 304 may enable the power distribution system 402 to minimize the amount of power utilized to operate the semiconductor chip by
15 reducing duplication components and enabling the buses 208 and 210 to share the power amplifiers 204 and 206, the standby power amplifier 218, and the voltage detector 410. The shorting of the voltage buses 208 and 210 may reduce noise, such as current/voltage spikes or drops, and provide access to another voltage source for each of the circuits.

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Furthermore, each of the buses 208 and 210 may also have different capacitances, which may effect the time it takes for the buses 208 and 210 to reach a predetermined voltage level for operation. As noted above, these capacitances may be represented by

the array capacitor 406 and the periphery capacitor 408. For instance, during the power-up mode each of the array and periphery circuitry 212 and 214 has a different capacitance that influences the amount of time it takes to reach a certain voltage. The bridge circuit 304 may improve the operation of power distribution system 402 in the semiconductor chip by coupling the buses 208 and 210 together to reduce the total time it takes for both buses 208 and 210 to reach a predetermined operational voltage. The advantage of coupling these buses 208 and 210 together with regard to the ramp-up time is explained in greater detail with respect to FIG. 5.

In FIG. 5, a graph 500, is shown with different illustrations of the ramp-up time for different circuits to reach an operational voltage. The ramp-up time period may be the amount of time a circuit uses to reach a specified voltage that is used to operate the circuit, for instance. In the graph 500, a first ramp-up time period 502 may be associated with a circuit that reaches the specified voltage level V at a time t_a . A second ramp-up time period 504 may be associated with a circuit that reaches the specified voltage level V at a time t_b , while a third ramp-up time period 506 may be associated with a circuit that reaches the specified voltage level V at a time t_c .

In operating the semiconductor chip, it may be beneficial to reach the voltage level V in the least amount of time. However, the capacitance of the respective circuits, such as the array circuitry 212 and the periphery circuitry 214, may influence the time it takes for each circuit to reach the specified voltage level V . This may be more clearly

understood by concurrently viewing FIGs. 4 and 5. For instance, the periphery voltage bus 210 may have a capacitor 406 that results in a ramp-up time period 502, while the array voltage bus 208 may have an array capacitor 408 that results in a ramp-up time period 506. If the bridge circuit 304 is open, each of the buses 208 and 210 may reach the specified voltage level V at the different times t_A and t_C . However, if the bridge circuit 304 couples the two buses 208 and 210 together, then the buses 208 and 210 may follow the ramp-up time period 504 and reach the specified voltage level V at times t_B . As a result, the power distribution system 402 may decrease the time it takes for both buses 208 and 210 to reach the specified voltage level V . Accordingly, the power distribution system 402 may reduce the total amount of time to reach an operational voltage, which may allow the semiconductor chip to become operational faster. A more detailed description of an exemplary embodiment of the bridge circuit 304 that is adapted to provide this flexibility is further explained with reference to FIG. 6.

In FIG. 6, a schematic diagram depicting an exemplary embodiment of a bridge circuit 600, which may be used in the semiconductor chip 302 of FIG. 3 or the power distribution system 402 of FIG. 4, is illustrated. For clarity, FIG. 6 should be viewed concurrently with FIGs. 3 and 4 to provide a better understanding of the connectivity and operation of the bridge circuit 600. The bridge circuit 600 may include a first portion 601 that receives control signals and a second portion 603 that isolates the buses 208 and 210 from each other or couples the buses 208 and 210 together. The first section 601 may include a first input 602 and a second input 604 of the bridge circuit 600, which may

receive control signals. The first input 602 may be coupled to a logic device 606, such as a “NAND” gate, and be adapted to receive a first control signal. As an example, the first control signal may be a power-up control signal delivered from the voltage detector 410 to indicate the power-up mode. The second input 604 may be coupled to a first inverter 608 and is adapted to receive a second control signal, which may indicate the power-up mode, the idle mode, the activation mode, the read/write burst mode, the standby mode, and/or the power-down mode. The second control signal may be delivered from the regulator control 412. The first inverter 608 may convert the second control signal to a “high” or “low” signal that is opposite of the signal received. The inverted second control signal is then delivered to the logic device 606. The logic device 606 may receive the first control signal and the inverted second control signal and combine the signals into an output signal.

Once the output signal is generated, it may be delivered to the second section 603 of the bridge circuit 600 to isolate buses 208 and 210 from each other or to couple the buses 208 and 210 together. The output signal is delivered to a second inverter 610, which converts the output signal from a “low” or a “high” signal to a signal that is the opposite of the signal received. The inverted output signal is then delivered to a logic gate 612, which is coupled between a first output 614 and a second output 616. As an exemplary embodiment, the logic gate 612 may be a P-channel (MOSFET) transistor with a gate connected to the output of the second inverter 610 and a source and a drain connected to the buses 208 and 210, respectively. The first output 614 may connect to

the periphery voltage bus 210 and the second output 616 may connect to the array voltage bus 208. Once the logic gate 612 receives the inverted output signal, the logic gate 612 may open to isolate the buses 208 and 210 or may close to couple the buses 208 and 210 together. The operation of the bridge circuit 600 is described below for each of the
5 various modes.

For instance, if the first input 602 is a “low” control signal or if the second input 604 is a “high” control signal, then the logic gate 612 may close to couple the outputs 614 and 616 together. However, if the first input 602 is a “high” control signal and the
10 second input 604 is a “low” control signal then the logic gate 612 may remain open, which isolates outputs 614 and 616 from each other. In an exemplary embodiment, the power distribution system 402 may be adapted to provide the power-up control signal on the first input 602, and the activation, read/write burst, standby, and/or power down control signals on the second input 604. In this example, the power-up, activation, and
15 read/write burst control signals are “low” when the associated mode is active and “high” when the associated mode inactive. Conversely, the idle, standby, and power-down control signals are “high” when the associated mode is active and “low” when the associated mode is inactive. As a result, the power-up, idle, standby, and power-down control signals couple the buses 208 and 210 together, while the activation, and
20 read/write burst control signals isolate the buses 208 and 210 from each other. As such, the control signals may be delivered to the bridge circuit 600 to open or close the logic

gate 612. The operation of the bridge circuit 600 may be further described in the process flow diagram of FIG. 7.

FIG. 7 is a process flow diagram showing the operation of a bridge circuit in accordance with embodiments of the present invention. In the diagram, generally referred to by reference numeral 700, a bridge circuit, such as the bridge circuit 304 or 600, may be implemented and utilized in a device, such as the semiconductor chip 302 of FIG. 3. The process flow diagram may be better understood by concurrently viewing FIGs. 3, 4 and 6. The process begins at block 702. At block 704, the amplifiers 204, 206 or 218 may receive power. As set forth above, the amplifiers 204, 206 or 218 may include multiple power amplifiers that are associated with specific circuits. At block 706, a voltage may be applied on a first and a second bus, such as buses 208 and 210. Also, the bridge circuit 304 may receive control signals from the voltage detector 404 or 410 and/or the regulator control 412. The control signals may correspond to the power-up, idle, activation, read/write burst, standby, and/or power-down mode.

Depending on the control signal received, the bridge circuit 304 determines whether to short the buses 208 and 210 together, as shown in block 710. The opening or closing of the bridge circuit 304 may be controlled by control signals received by the bridge circuit 304 and the signal received at the logic gate 612 within the bridge circuit 304. If the control signals indicate that the bridge circuit 304 should couple the buses 208 and 210, then the first bus 208 and the second bus 210 may be shorted together through

the bridge circuit 304 at block 712. The coupling of the buses 208 and 210 may allow the buses 208 and 210 to maintain a similar voltage and share components, as discussed above. However, if the control signals indicate that the bridge circuit 304 should be open, then the buses 208 and 210 may be isolated to maintain different voltages by operating
5 independently of each other, as shown at block 714. At block 716, the bridge circuit 304 may determine if a power down signal, which may indicate that the system is being powered or may result from a hard shutdown, has been received. If the bridge circuit 304 determines that the power down signal has not been received, then the bridge circuit 304 may continue to monitor the control signals at block 710. However, if a power down
10 signal has been received, the process ends at block 718.

While the invention may be susceptible to various modifications and alternative forms, specific embodiments have been shown by way of example in the drawings and have been described in detail herein. However, it should be understood that the invention
15 is not intended to be limited to the particular forms disclosed. Rather, the invention is to cover all modifications, equivalents, and alternatives falling within the spirit and scope of the invention as defined by the following appended claims.